

emiconductor, Inc.

5

0

9

U

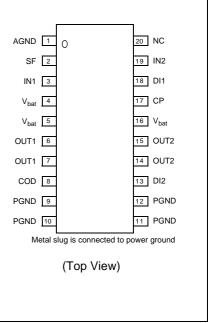
Ũ

Û

0

Š.

LL.



ORDE	ORDERING INFORMATION				
Device	Temperature Range	Package			
MC33186DH1R2	-40°C to +125°C	HSOP20			

For More Information On This Product, Go to: www.freescale.com

Ratings	Symbol	Min	Тур	Max	Unit
ELECTRICAL RATINGS				<b>1</b>	
Supply Voltage - Static Destruction Proof - Dynamic Destruction Proof t < 0,5s	Vbat Vbat	- 1 - 2		28 40	V
Logic Inputs (IN1, IN2, DI1, DI2, CODE)	U	- 0.5		7	V
Output Status - Flag SF	U <sub>SF</sub>	- 0.5		7	V
THERMAL RATINGS		·			
Junction Temperature	Тj	- 40		+150	°C
Storage Temperature	Τ <sub>s</sub>	- 55		+125	°C
Ambient Temperature	Т <sub>а</sub>	- 40		+125	°C
Thermal Resistance (with power applied on 2 power MOS)	Rth <sub>JC</sub>			+1,5	K/W

# **ELECTRICAL CHARACTERISTICS.**Tj : from -40°C to +150 °C, Vbat from 5 V to 28 V, unless otherwise note. Typical values reflect approximate mean at 25°C, nominal VCC, at time of device characterization.

Characteristics	Symbol	Min	Тур	Max	Unit
RANGE OF VALIDITY	ŀ	4	ł	• • • •	
	Vbat T <sub>j</sub>	5 -40		28 150	v °C
POWER SUPPLY					
Operating Range : - Static - Dynamic ( t < 500ms )	Vbat Vbat	5		28 40	V V
Stanby current - f = 0 to 10KHz ; I <sub>OUT</sub> = 0A	I Vbat			35	mA
Vbat-undervoltage switch-off (without load) - Switch-off Voltage - Switch-on Voltage - Hysteresis		4.15 4.5 150	4.4 4.75	4.65 5	V V mV
CHARGE-PUMP SUPPLY					
- Vbat = 4.15 V - Vbat < 40V	Vcp - Vbat Vcp - Vbat	3.35		20	V V
LOGIC INPUTS					
Input High	VinH	3.4			V
Input Low	VinL			1.4	V
Input Hysteresis	U	0.7	1		V
Input Current (IN1, IN2, DI1) - U <sub>IN</sub> = 0V	I	- 200	- 80		μΑ
Input Current (DI2,COD) - U <sub>DI2</sub> = 5V	I <sub>DI2</sub>		25	100	μΑ

**ELECTRICAL CHARACTERISTICS.**Tj : from -40°C to +150 °C, Vbat from 5 V to 28 V, unless otherwise note. Typical values reflect approximate mean at 25°C, nominal VCC, at time of device characterization.

Characteristics	Symbol	Min	Тур	Max	Unit
POWER OUTPUTS : OUT1, OUT2		1		L	
Switch on resistances : R <sub>OUT - Vbat</sub> ; R <sub>OUT - GND</sub>					
- Vbat =5 to 28V ; Ccp = 0 to 33nF				300	mΩ
Current Limitation Controlled Peak Value					
Switch-off Current	(I <sub>OUT</sub> ) max	5.2	6.5	7.8	А
Switch-off Time	ta	15	20.5	26	μs
Blanking Time	tb	12	16.5	21	μs
High Side Overcurrent Detection Low Side Overcurrent Detection (4)	I <sub>OCHS</sub> I <sub>OCLS</sub>	11 8			A A
Leackage Current - Output Stage Switched off				100	μΑ
Free-Wheeling Diode Forward Voltage - I <sub>OU</sub> = 3A	U <sub>D</sub>			2	V
Free-Wheeling Diode Reverse Recovery Time	trr	100			ns
- Switch-off Temperature - Hysteresis		160 20		190 30	°C °C
OUTPUT STATUS FLAG (Open drain output)		1		L	
Output High (SF not set) U <sub>SF</sub> = 5V	I <sub>SF</sub>			10	μΑ
Output Low (SF set) ISF = 300 µA	VSF			1	V
TIMING		·	·		
PWM frequency - C <sub>CP</sub> = 33nF	f			10	KHz
Maximum Switching Frequency During Current Limitation - Vbat = 628VC <sub>CP</sub> = 33nF	f			20	KHz
Output ON Delay IN1 <sub>&gt;</sub> OUT1 or IN2 <sub>&gt;</sub> OUT2	t <sub>don</sub>			15	μs
Output OFF Delay IN1 <sub>&gt;</sub> OUT1 or IN2 <sub>&gt;</sub> OUT2	t <sub>doff</sub>			15	μs
Output Switching Time - C <sub>CP</sub> = 0 to 33nF OUTiHOUTiL, OUTiLOUTiH, IOUT= 3A	t <sub>r</sub> , t <sub>f</sub>	2		5	μs
Disable Delay Time DliOUTi	t <sub>ddis</sub>			8	μs
Turn off in Case of Over-current or Over-temperature			4		μs
Power On Delay Time (Ccp = 33nF)			1	5	ms

MC33186

#### **TRUH TABLE**

Device State		Input Co	onditions		Sta	itus	Out	puts
	DI1 (3)	DI2 (3)	IN1	IN2	SF (5)	SF (6)	OU1	OU2
1-Forward	L	н	н	L	Н	Н	Н	L
2-Reverse	L	Н	L	Н	Н	Н	L	н
3-Free Wheeling Low	L	Н	L	L	Н	Н	L	L
4-Free Wheeling High	L	н	н	Н	Н	Н	Н	н
5-Disable 1	Н	Х	Х	Х	L	Н	Z	Z
6-Disable 2	Х	L	Х	Х	L	Н	Z	Z
7-IN1 Disconnected	L	н	Z	Х	Н	Н	Н	х
8-IN2 Disconnected	L	Н	Х	Z	Н	Н	х	н
9-DI1 Disconnected	Z	Х	Х	Х	L	Н	Z	Z
10-DI2 Disconnected	Х	Z	Х	Х	L	Н	Z	Z
11-Current Limit.active	L	Н	Х	Х	Н	Н	Z	Z
12-Undervoltage (1)	Х	Х	Х	Х	L	L	Z	Z
13-Over-temperature (2)	Х	Х	Х	Х	L	L	Z	Z
14-Over-current (2)	Х	Х	Х	Х	L	L	Z	Z

#### NOTE :

NOTE: (1) In case of undervoltage, tristate and status-flag are reset automatically. (2) Whenever over-current or over-temperature is detected, the fault is stored (i.e.status-flag remains low). The tristate conditions and the status-flag are reset via DI1 (IN1) or DI2 (IN2). Pinnames in brackets refer to coding pin (COD=Vcc). (3) If COD = Vcc then DI1 and DI2 are not active. (4) In case of over-current, the time when the current is greater than 7,8A is lower than 30µs, with a maximum frequency of 1kHz.

(5) COD=nc or GND (6) COD = VCC

L = Low H = High

X = High or LowZ = High impedance (all output stage transistors are switched off ).

Pin	Name	Description
9, 10, 11, 12 Metal slug	GND	Power Ground
1	GND	Analog ground
2	Output Status- flag (SF)	Open drain output, active low. Is set according to the truth table .
3,13 18, 19	Inputs IN1,IN2 DI1,DI2, COD	Voltage controlled inputs with hysteresis
8	COD	When not connected or connected to GND, a stored failure will be reset by change of the voltage-level on DI1 or DI2. When connected to Vcc, the disable pin DI1 and DI2 are inactive. A stored failure will be reset by change of the voltage-level on IN1 or IN2.
6, 7, 14, 15	OUT1 , OUT2	H-Bridge outputs with integrated free-wheeling diodes.
4, 5, 16	Vbat	<ul> <li>The pins 4 and 5 are internally connected. These pins supply the left high side and the analogue/logic part of the device.</li> <li>The pin 16 supplies the right high side and the charge pump.</li> <li>The pins 4, 5 and 16 should be connected together on the printed circuit board with connections as short as possible.</li> <li>Supervision and protection functions <ul> <li>a) Supply voltage supervision</li> <li>The supply voltage is supervised. If it is below its specific threshold, the power stages are switched in tristate and the status flag is switched low.</li> <li>If the supply voltage is over the specific theshold again, the power stage switches independently into normal operation, according to the input pins and the status flag is reset .</li> <li>b) Thermal supervision</li> <li>In case of over-temperature the power stages are switched in tristate independent of the inputs signals and the status flag is switched low.</li> <li>If the level changes from high to low on DI1 (IN1) or low to high on DI2 (IN2), the output stage switches on again if the temperature is below the specified limit . The status-flag is reset to high level (Pinnames in brackets refer to coding pin=Vcc).</li> <li>c) Supervision of overcurrent</li> <li>If overcurrent is detected the power stages are independent of the inputs signals switches on again and the status flag is reset to high level (Pinnames in brackets refer to coding pin=Vcc).</li> <li>c) Supervision of overcurrent</li> <li>If the level changes from high to low on DI1 (IN1) or low to high on DI2 (IN2) the output stage switches on again and the status flag is reset to high level (Pinnames in brackets refer to coding pin = Vcc).</li> <li>The output stage switches on again and the status flag is reset to high level (Pinnames in brackets refer to coding pin = Vcc).</li> </ul> </li> </ul>
		d) Current limiting The maximum current which can flow under normal operating conditions is limited to Imax = $6,5A +/- 20\%$ . When the maximum current value is reached, the output stages are switched tristate for a fixed time. According to the time constant the current decreases until the next switch on occurs. See page 8 for schematics.

MC33186 Freescale Semiconductor, Inc.

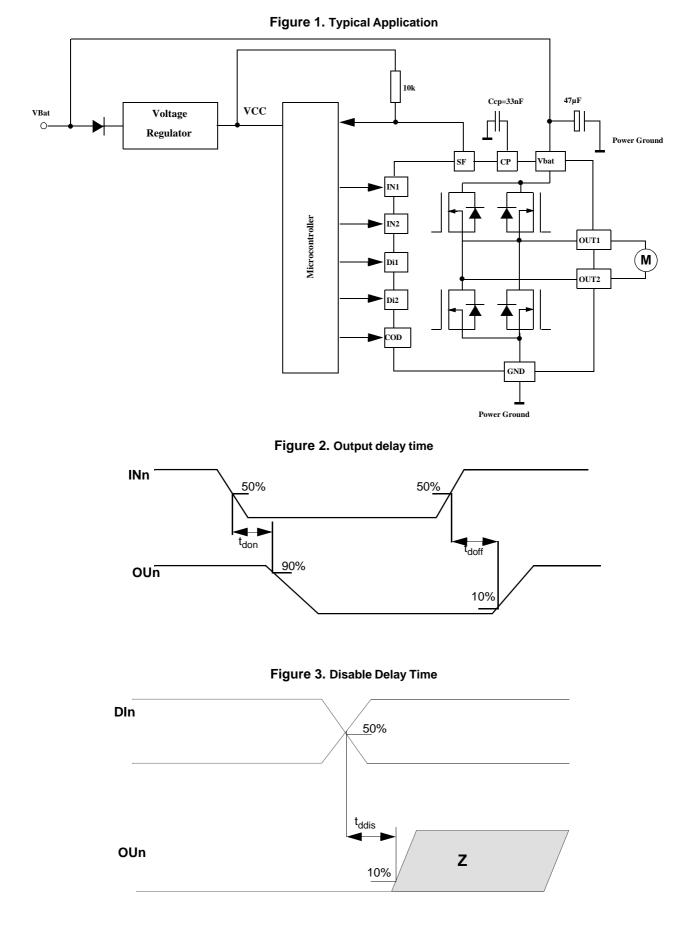
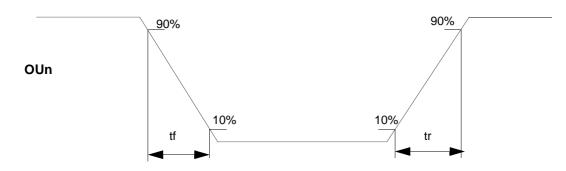
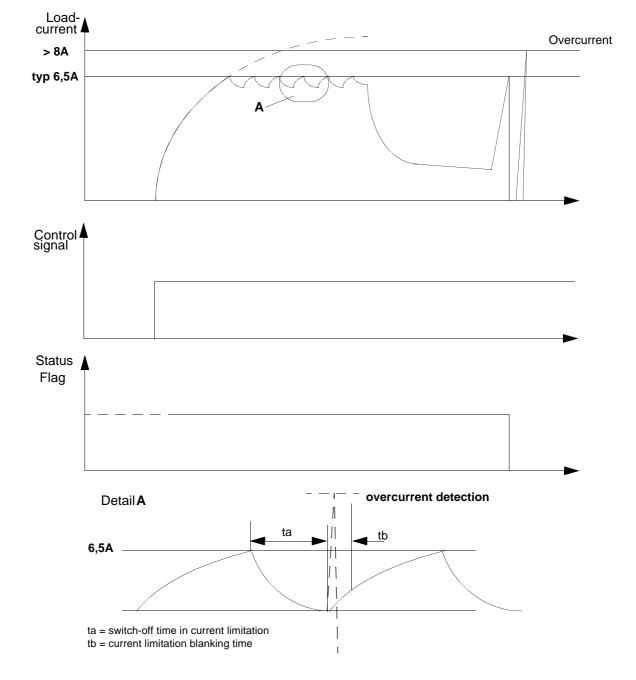




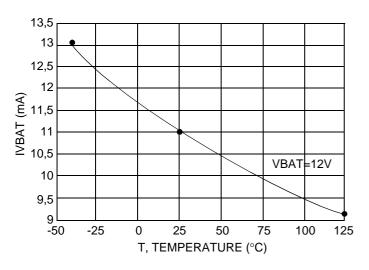
Figure 4. Output Switching Time



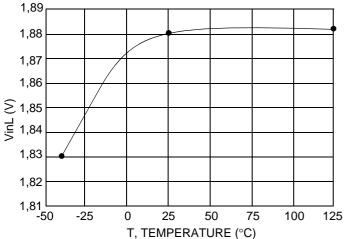




#### Figure 6 - Standby Current versus Temperature









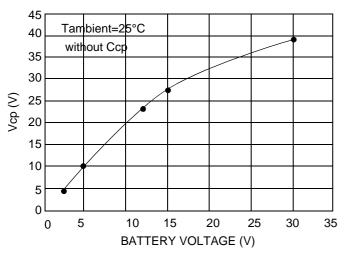
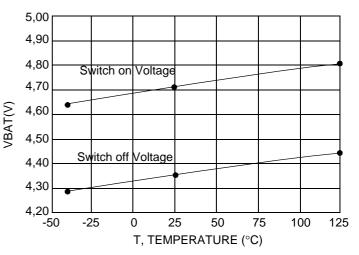
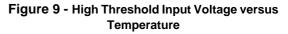
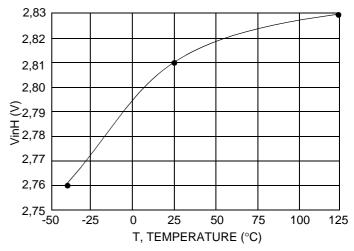


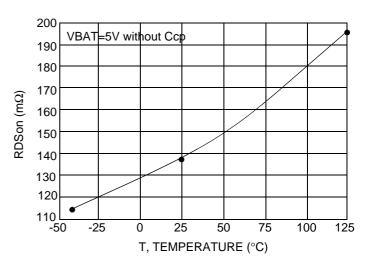
Figure 7. VBAT Undervoltage versus Temperature













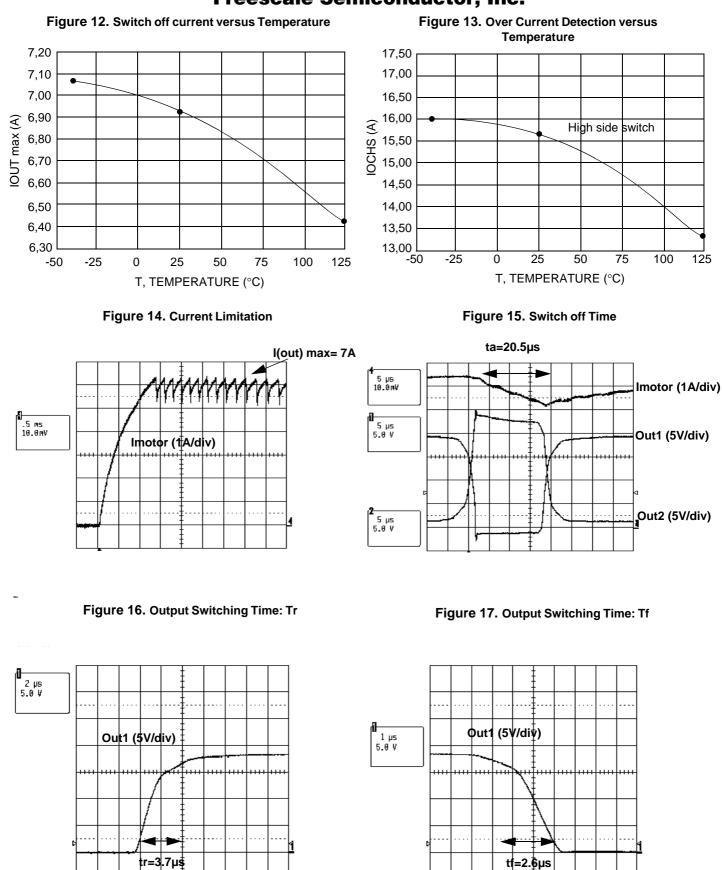
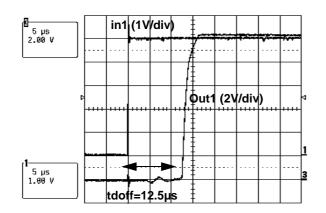


Figure 18. Output OFF Delay

Figure 19. Output ON Delay



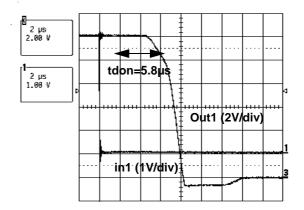
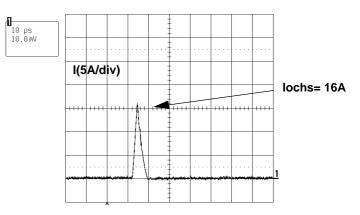
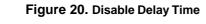
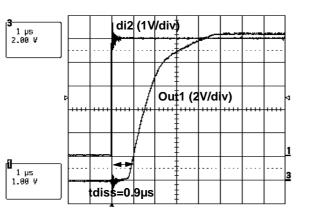


Figure 21. High side Overcurrent Detection







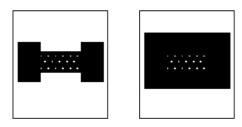
# Freescale Semiconductor, Inc.

The HSOP20 package is designed for enhanced thermal performance. The particularity of this package is its copper baseplate on which the power die is soldered. The baseplate is soldered on a PCB to provide heat flow to the ambient and also to provide a large thermal capacitance.

Of course, the more copper area on the PCB, the better the power dissipation and transient behaviour.

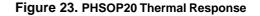
We characterized the HSOP20 on a double side PCB. The bottom side area of the copper is 7.8  $cm^2$ . The top surface is 2.7  $cm^2$ , see Figure 22.

Figure 22. PCB Test Layout



Top Side

Bottom Side



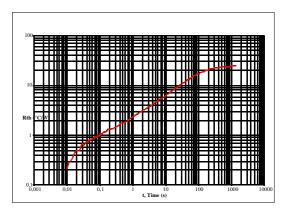
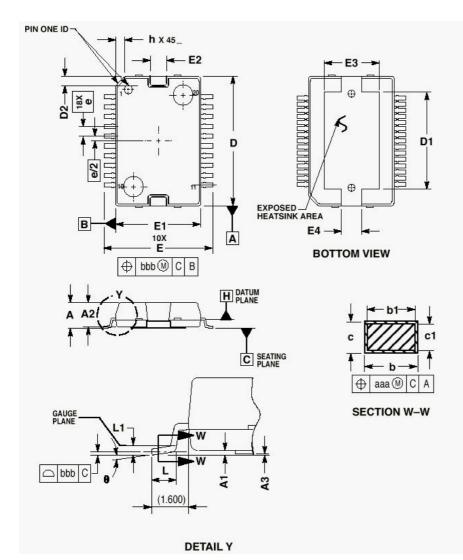


Figure 23 shows the thermal response with the device soldered on to the test PCB described on figure 22.

#### **CASE OUTLINES**



- NOTES:
  - 1. CONTROLLING DIMENSION: MILLIMETER. 2. DIMENSIONS AND TOLERANCES PER ASME Y14.5M, 1994.
- Y14.5M, 1994. 3. DATUM PLANE -H- IS LOCATED AT BOTTOM OF LEAD AND IS COINCIDENT WITH THE LEAD WHERE THE LEAD EXITS THE PLASTIC BODY AT THE BOTTOM OF THE PARTING LINE. 4. DIMENSIONS D AND E1 DO NOT INCLUDE MOLD PROTRUSION. ALLOWABLE PROTRUSION IS 0.150 PER SIDE. DIMENSIONS D AND E1 DO INCLUDE MOLD MINATCH AND APE INCLUDE MOLD MISMATCH AND ARE DETERMINED AT DATUM PLANE -H-.
- DELETIME AND A DATA TO TINCLUDE DAMBAR PROTRUSION & DOES NOT INCLUDE DAMBAR PROTRUSION ALLOWABLE DAMBAR PROTRUSION SHALL BE 0.127 TOTAL IN EXCESS OF THE & DIMENSION AT MAXIMUM MATERIAL CONDITION CONDITION.
- CONDITION.
   DATUMS –A- AND –B- TO BE DETERMINED AT DATUM PLANE –H–.
   DIMENSION D DOES NOT INCLUDE TIEBAR PROTRUSIONS. ALLOWABLE TIEBAR PROTRUSIONS ARE 0.150 PER SIDE.

	MILLIMETERS					
DIM	MIN	MAX				
Α	3.000	3.400				
A1	0.100	0.300				
A2	2.900	3.100				
A3	0.00	0.100				
D	15.800	16.000				
D1	11.700	12.600				
D2	0.900	1.100				
E	13.950	14.450				
E1	10.900	11.100				
E2	2.500	2.700				
E3	6.400	7.200				
E4	2.700	2.900				
L	0.840	1.100				
L1	0.350 BSC					
b	0.400	0.520				
b1	0.400	0.482				
C	0.230	0.320				
c1	0.230	0.280				
e	1.270	BSC				
h	_	1.100				
Ð	0	8				
222	0.200					

0.100

bbb

Motorola reserves the right to make changes without further notice to any products herein to improve reliability, function or design. Motorola does not assume any liability arising out of the application or use of any product or circuit described herein ; neither does it convert any licence under its patent rights of others. Motorola products are not authorized for use as components in life support devices or systems intended for surgical implant into the body or intended to support or sustain life. Buyer agrees to notify Motorola of any such intended end use whereupon Motorola shall determine availability and suitability of its products for the use intended. Motorola and (A) are registered trademarks of Motorola, Inc. Motorola, Inc. is an Equal Employment opportunity/Affirmative Action Employer.